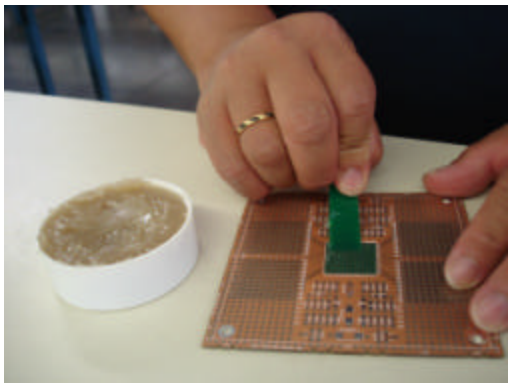
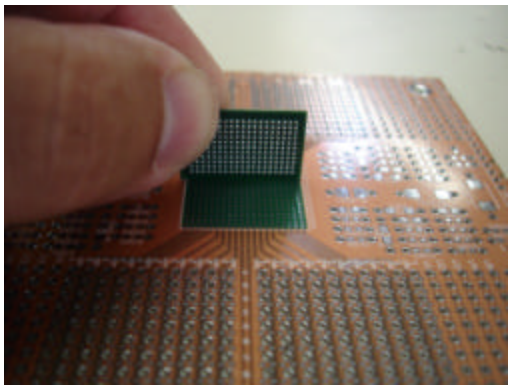
BGA SchmartBoard/ez Instructions

Method 1- Requires Solder Flux in Paste Form, and Solder

Step 1 Put Flux over top of area where the BGA will be placed.

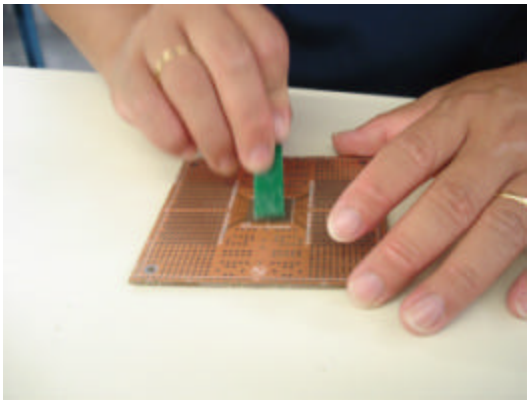


Step 2 Place the BGA on the Board

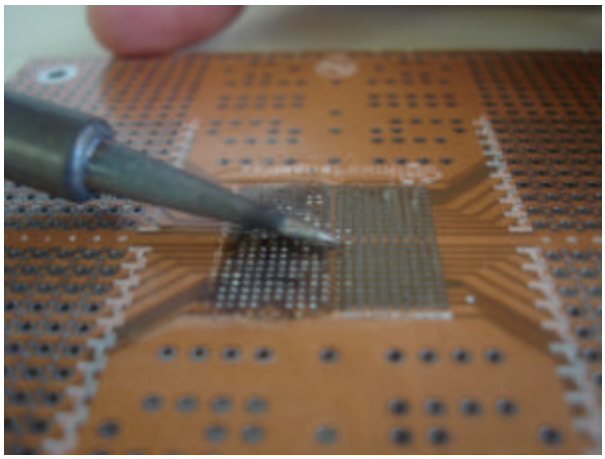


Step 3 Tape the BGA onto the board(Taped both horizontally and vertically)

Step 4 Turn the board over and liberally rub flux over the area underneath where the BGA is taped down



Step 5 Using your soldering Iron and solder, melt the solder and rub the molten solder into the holes. Spend time to assure that the holes are properly filled with solder. *IMPORTANT- Start with the holes in the center and work your way outward. This will keep the BGA level on the board.*



Step 6 Clean off the board with wet towel AND LET DRY. Test your circuit. If you missed a ball or have an open, go back and retouch the specific ball (Remember to reapply flux to assure no shorts are created)

Tips for Success

Take your time and make sure that you get solder in each hole in which a ball needs to be soldered. Be sure to use flux. We have found that FLUX PASTE is the best solution and recommend it over liquid flux. If you find that any balls did not make a solder connection, put down some more flux paste and focus on this area with more solder and assure that solder gets into the hole. For melting and spreading the solder onto the board, a larger tip may work best, for focusing on individual holes when retouching, a finer tip may work better. 850F+ degrees is a good temperature for these lead free boards. If you have access to a re-flow oven, lucky you! Follow the instructions below.

Method 2- Requires a Re-flow Oven, Solder Paste and Solder Flux in Paste Form

Step 1 Put Flux over top of area where the BGA is placed.
Step 2 Place BGA onto board
Step 3 Put Solder Paste over the bottom of the board(Under BGA area)
Step 4 Run through the re-flow oven